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**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claim 1 (currently amended): An MIM capacitor comprising:  
a lower electrode comprising a plurality of metal layers including a top metal layer;  
an upper electrode; and  
a dielectric layer positioned between said lower electrode and said upper electrode,  
wherein the top metal layer includes an insulating metal oxide layer disposed on the entire surface thereof; and  
wherein the lower electrode is formed by a first titanium layer, a platinum layer, a gold layer, and a second titanium layer; and  
wherein the insulating metal oxide layer is in direct contact with a surface of the dielectric layer.

Claim 2 (original): An MIM capacitor according to Claim 1, wherein the top metal layer comprises a material selected from transition metals and alloys thereof which are capable of forming insulating layers by oxidation.

Claim 3 (previously presented): An MIM capacitor according to Claim 1, wherein the top metal layer comprises one of said first and second titanium layers.

Claim 4 (original): An MIM capacitor according to Claim 1, wherein said dielectric layer comprises silicon nitride.

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**Claim 5 (original): An MIM capacitor according to Claim 4, wherein the surface of said dielectric layer is oxidized to form an oxidized silicon nitride layer.**

**Claims 6-10 (canceled).**

**Claim 11 (original): A microwave monolithic integrated circuit comprising an MIM capacitor as set forth in Claim 1.**

**Claim 12 (canceled).**

**Claim 13 (previously presented): An MIM capacitor according to Claim 1, wherein the upper electrode is formed by a titanium layer, a platinum layer, and a gold layer.**

**Claim 14 (previously presented): An MIM capacitor according to Claim 1, wherein the lower electrode is formed, in order, by the first titanium layer, the platinum layer, the gold layer, and the second titanium layer.**

**Claim 15 (previously presented): An MIM capacitor according to Claim 1, wherein the upper electrode is formed, in order, by a titanium layer, a platinum layer, and a gold layer.**